

Features

- Low start-up voltage: 0.7V (Typ.)
- High efficiency: $2.7V \leq V_{OUT} \leq 5.0V$ upper 90% (Typ.)
- High output voltage accuracy: $\pm 2.5\%$
- Output voltage: 2.7V, 3.0V, 3.3V, 5.0V
- Output current up to 200mA
- Ultra low supply current I_{DD} : 5 μ A (Typ.)
- Low ripple and low noise
- Low shutdown current: 0.1 μ A (Typ.)
- TO92, SOT89, SOT23 and SOT23-5 package

Applications

- Palmtops/PDAs
- Portable communicators/Smartphones
- Cameras/Camcorders
- Battery-powered equipment

General Description

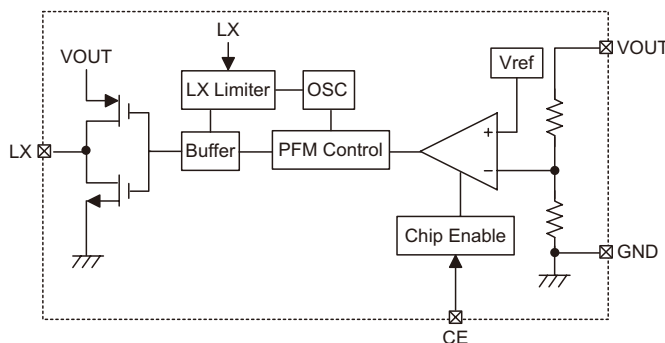
The HT77xxSA devices are a high efficiency PFM synchronous step-up DC-DC converter series which are designed to operate with both wire wound chip power inductors and also with multi-layered chip power inductors. The device series have the advantages of extremely low start-up voltage as well as high output voltage accuracy. Being manufactured using CMOS technology ensures ultra low supply current. Because of their higher operating frequency, up to 500 kHz, the devices have the benefits of requiring smaller outline type lower value external inductors and capacitors. The higher operating frequency also offers the advantages of much reduced audio frequency noise. The devices require only three external components to provide a fixed output voltage of 2.7V, 3.0V, 3.3V or 5.0V.

The HT77xxSA devices include an internal oscillator, PFM control circuit, driver transistor, reference voltage unit and a high speed comparator. They employ pulse frequency modulation techniques, to obtain minimum supply current and ripple at light output loading. These devices are available in space saving TO92, SOT89, SOT23 and SOT23-5 packages. For SOT23-5 package types, they also include an internal chip enable function to reduce power consumption when in the shutdown mode.

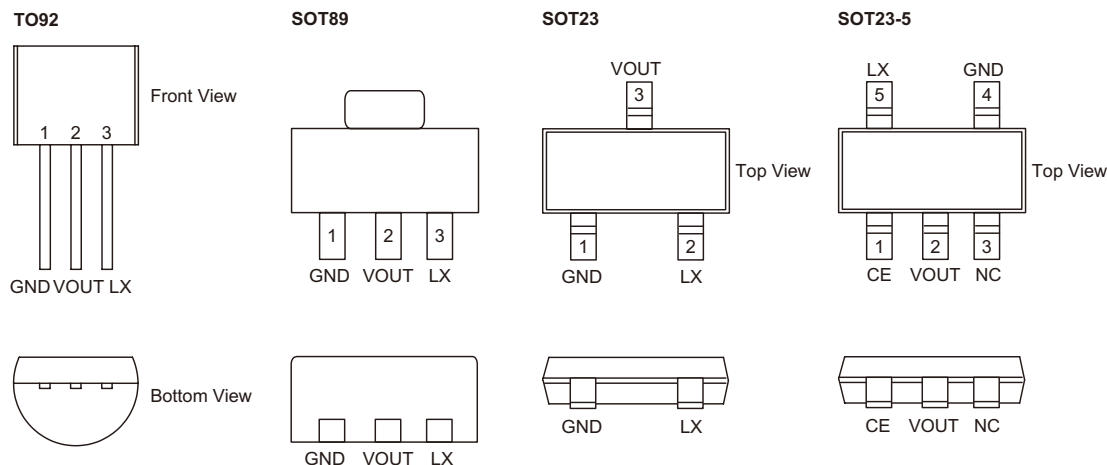
Selection Table

Part No.	Output Voltage	Tolerance	Package
HT7727SA	2.7V	$\pm 2.5\%$	TO92 SOT89 SOT23 SOT23-5
HT7730SA	3.0V		
HT7733SA	3.3V		
HT7750SA	5.0V		

Block Diagram



Pin Assignment



Pin Description

Pin No.				Pin Name	Description
TO92	SOT89	SOT23	SOT23-5		
—	—	—	1	CE	Chip enable pin, high active
2	2	3	2	VOUT	DC/DC converter output monitoring pin
—	—	—	3	NC	No connection
1	1	1	4	GND	Ground pin
3	3	2	5	LX	Switching pin

Absolute Maximum Ratings

Maximum Input Supply Voltage 6.5V Storage Temperature -50°C to 125°C
 Ambient Temperature Range -40°C to 85°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Electrical Characteristics

Ta= 25°C; V_{IN}= V_{OUT}×0.6; I_{OUT}= 10mA; unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{IN}	Input Voltage	—	—	—	6.0	V
ΔV _{OUT}	Output Voltage Tolerance		-2.5	—	+2.5	%
V _{START}	Starting Voltage(Fig.1)	V _{IN} : 0 to 2V, I _{OUT} =1mA	—	0.7	0.9	V
V _{HOLD}	Voltage Hold(Fig.1)	V _{IN} : 2 to 0V, I _{OUT} =1mA	—	—	0.7	V
I _{DD1}	Supply Current (Fig.2)	V _S =V _{OUT} +0.5V, Measured at VOUT Pin	—	5.0	—	μA
I _{DD2}	Un-load Supply Current (Fig.1)	V _{IN} =V _{OUT} ×0.6, I _{OUT} =0mA Measurement at LX	—	—	—	μA
I _{SHDN}	Shutdown Current	CE=GND	—	0.1	—	μA
I _{Limit}	Current Limit (Fig.1)	V _{OUT} ≤ 5.0V	650	800	—	mA
		2.7V ≤ V _{OUT} ≤ 3.3V	500	650	—	mA
V _{IH}	CE High Threshold	—	2.0	—	—	V
V _{IL}	CE Low Threshold		—	—	0.4	V
I _{LEAK}	LX Leakage Current (Fig.3)	V _S =5.5V, V _X =4V Measurement at the LX pin	—	0.05	—	μA
f _{OSC}	Oscillator Frequency (Fig.3)	V _S =V _{OUT} ×0.95 Measurement at the LX pin	—	500	—	kHz
D _{OSC}	Oscillator Duty Cycle (Fig.3)		—	80	—	%
η	Efficiency	2.7V ≤ V _{OUT} ≤ 5.0V, I _{OUT} =10mA	—	90	—	%

Note: Absolute maximum ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. The guaranteed specifications apply only for the test conditions listed.

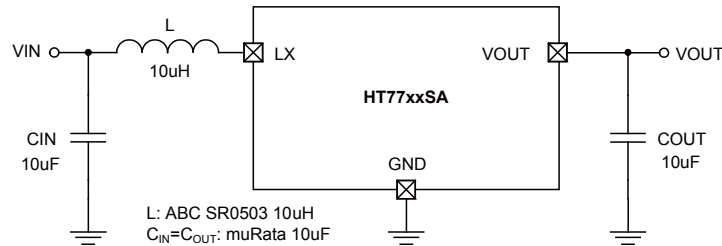


Fig.1

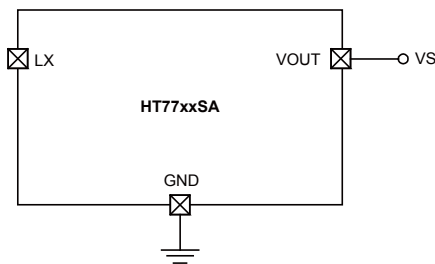


Fig.2

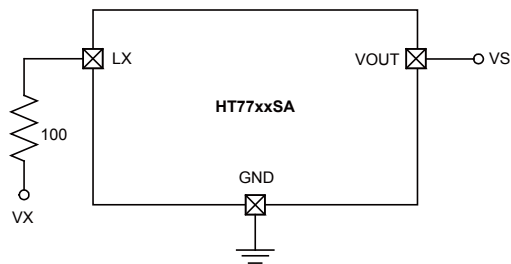
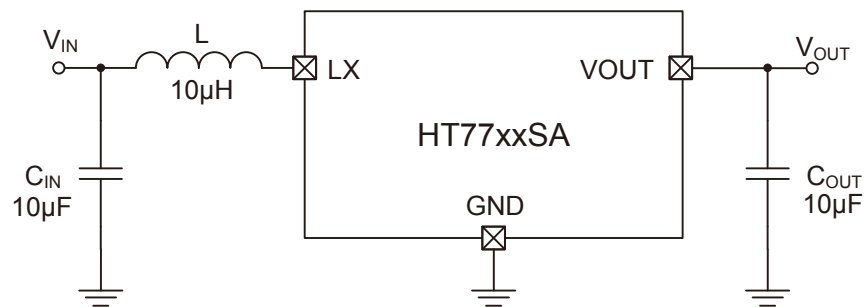


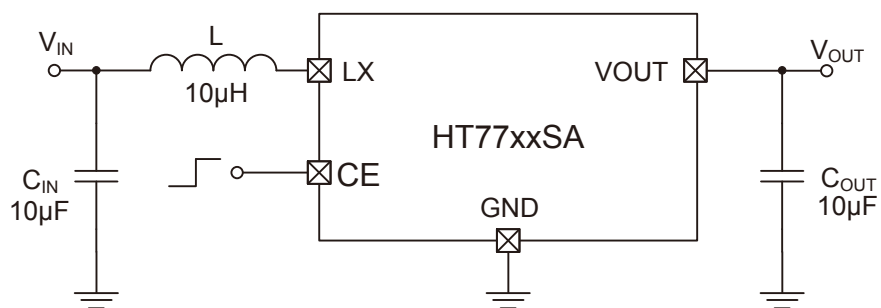
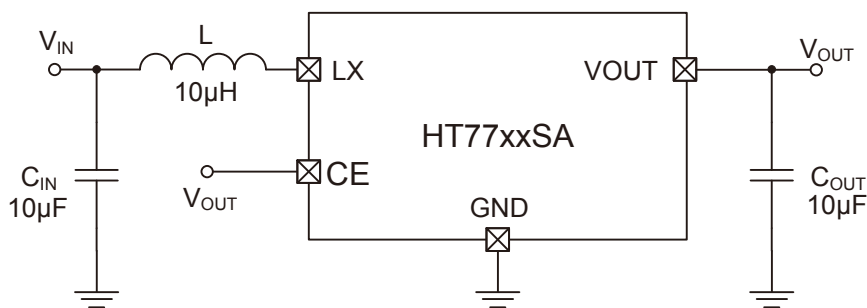
Fig.3

Application Circuits

Without CE Pin



With CE Pin



Functional Description

The HT77xxSA is a constant on time synchronous step-up converter, which uses a pulse frequency modulation (PFM) controller scheme. The PFM control scheme is inherently stable. The required input/output capacitor and inductor selections will not create situations of instability.

The device includes a fully integrated synchronous rectifier which reduces costs (includes reduce L and C sizes, eliminates Schottky diode cost etc.) and board area. A true load disconnect function ensures that the device is completely shutdown.

Low Voltage Start-up

The devices have a very low start up voltage down to 0.7V. When power is first applied, the synchronous switch will be initially off but energy will be transferred to the load through its intrinsic body diode.

Shutdown

During normal device operation, the EN pin should be either high or connected to the VOUT pin or the VIN power source. When the device is in the shutdown mode, that is when the EN pin is pulled low, the internal circuitry will be switched off. During shutdown, the PMOS power transistor will be switched off thus placing the output into a floating condition.

Synchronous Rectification

A dead time exists between the N channel and P channel MOSFET switching operations. In synchronous rectification, the P channel is replaced by a Schottky diode. Here the P channel switch must be completely off before the N channel switch is switched on. After each cycle, a 30ns delay time is inserted to ensure the N channel switch is completely off before the P channel switch is switched on to maintain a high efficiency over a wide input voltage and output power range.

Application Information

Inductor Selection

Selecting a suitable inductor is an important consideration as it is usually a compromise situation between the output current requirements, the inductor saturation limit and the acceptable output voltage ripple. Lower values of inductor values can provide higher output currents but will suffer from higher ripple voltages and reduced efficiencies. Higher inductor values can provide reduced output ripple voltages and better efficiencies, but will be limited in their output current capabilities. For all inductors it must be noted however that lower core losses and lower DC resistance values will always provide higher efficiencies.

The peak inductor current can be calculated using the following equation:

$$I_{L(PEAK)} = \frac{V_{OUT} \times I_O}{V_{IN} \times \eta} + \frac{V_{IN} \times (V_{OUT} - V_{IN})}{2 \times V_{OUT} \times L}$$

Where

V_{IN} = Input Voltage
 V_{OUT} = Output Voltage
 I_O = Output Current
 η = Efficiency
 L = Inductor

Capacitor Selection

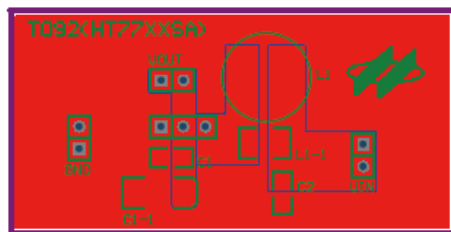
As the output capacitor selected affects both efficiency and output ripple voltage, it must be chosen with care to achieve best results from the converter. Output voltage ripple is the product of the peak inductor current and the output capacitor equivalent series resistance or ESR for short. It is important that low ESR value capacitors are used to achieve optimum performance. One method to achieve low ESR values is to connect two or more filter capacitors in parallel. The capacitors values and rated voltages are only suggested values.

Layout Considerations

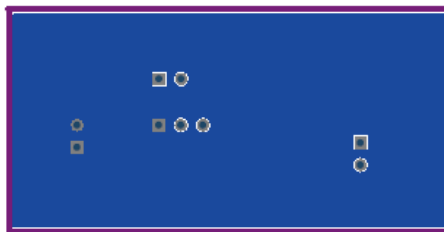
Circuit board layout is a very important consideration for switching regulators if they are to function properly.

Poor circuit layout may result in related noise problems. In order to minimise EMI and switching noise, note the following guidelines:

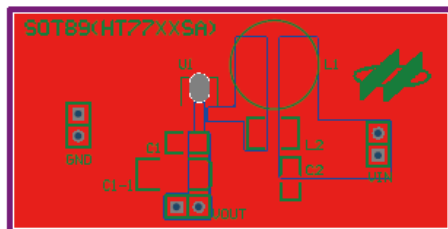
- All tracks should be as wide as possible.
- The input and output capacitors should be placed as close as possible to the VIN, VOUT and GND pins.
- A full ground plane is always helpful for better EMI performance.



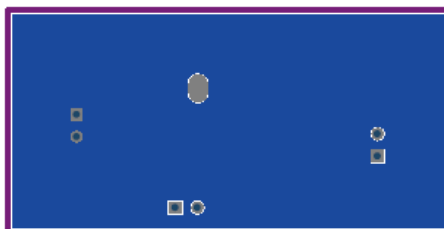
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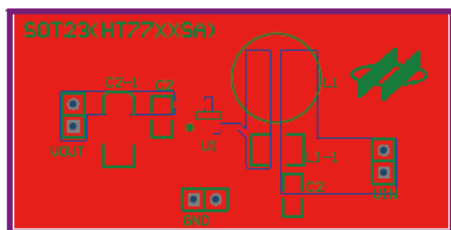
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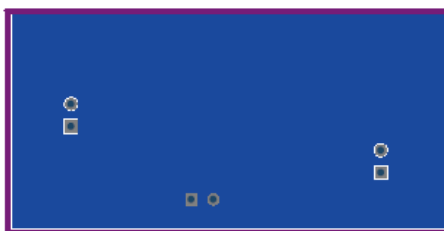
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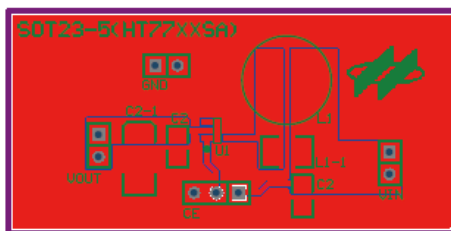
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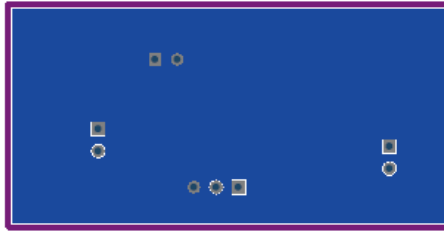
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Typical Performance Characteristics

HT7750SA

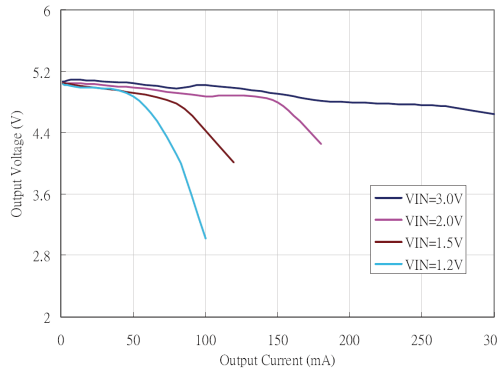


Fig 1. Output Voltage vs. Output Current

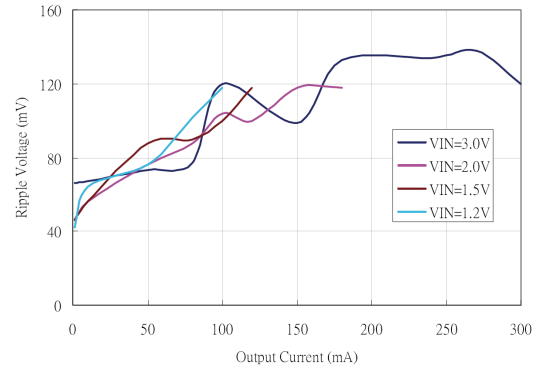


Fig 4. Ripple Voltage vs. Output Current

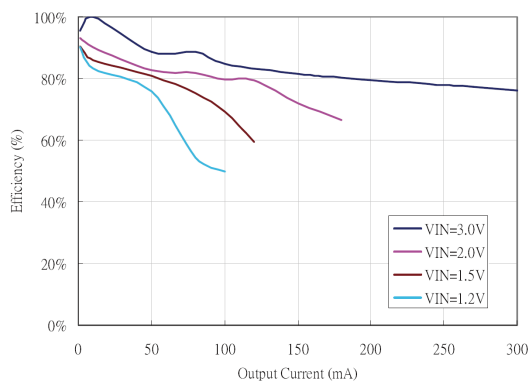


Fig 2. Efficiency vs. Output Current

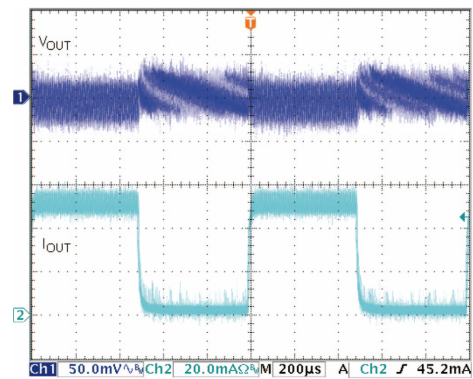


Fig 5. Load Transient Response
($L=10\mu\text{H}$, $C_{\text{IN}}=C_{\text{OUT}}=10\mu\text{F}$, $V_{\text{IN}}=3.0\text{V}$)

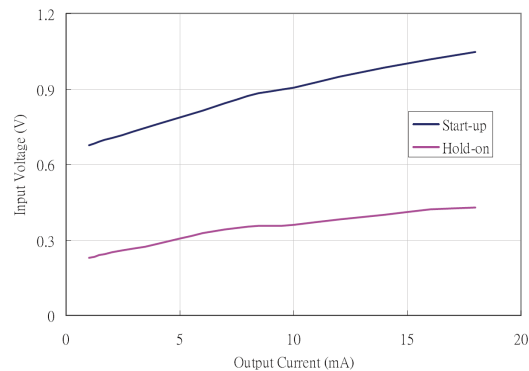


Fig 3. Start-up & Hold-on Voltage

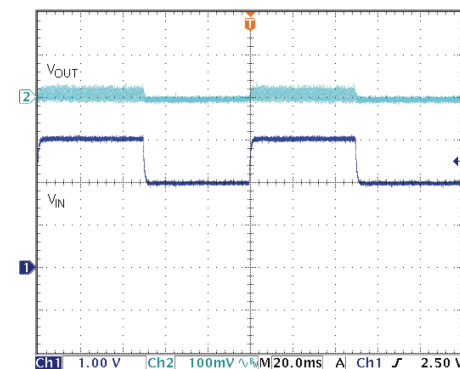


Fig 6. Line Transient Response
($L=10\mu\text{H}$, $C_{\text{IN}}=C_{\text{OUT}}=10\mu\text{F}$, $V_{\text{IN}}=3.0\text{V}$)

HT7733SA

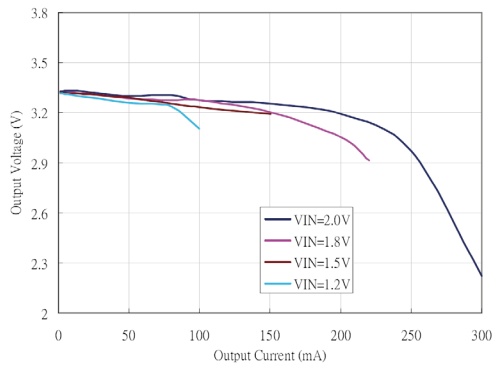


Fig 7. Output Voltage vs. Output Current 0%

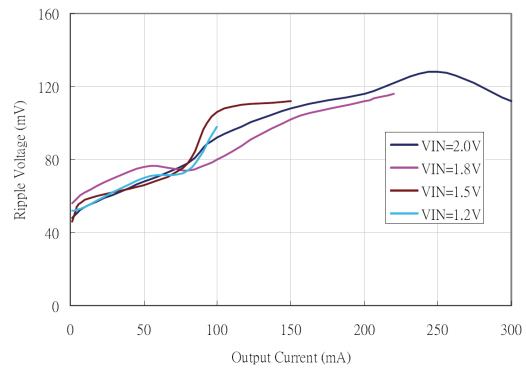


Fig 10. Ripple Voltage vs. Output Current

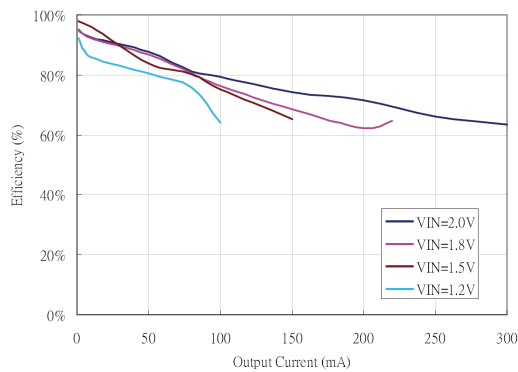


Fig 8. Efficiency vs. Output Current

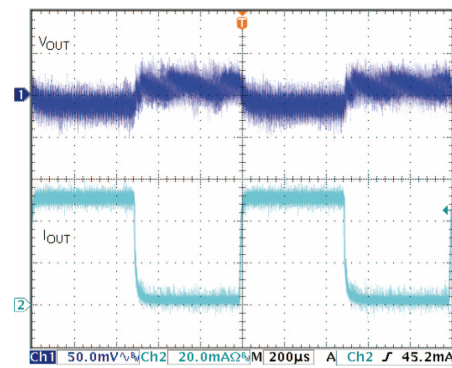


Fig 11. Load Transient Response
(L=10μH, CIN=COUT=10μF, VIN=1.98V)

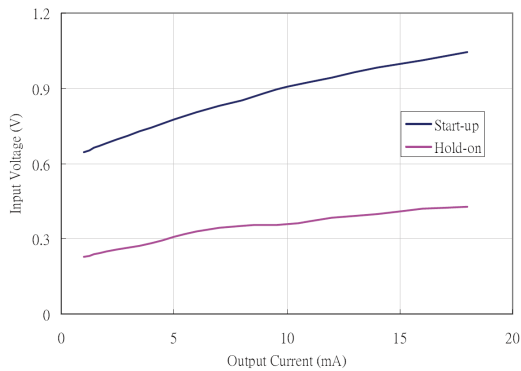


Fig 9. Start-up & Hold-on Voltage

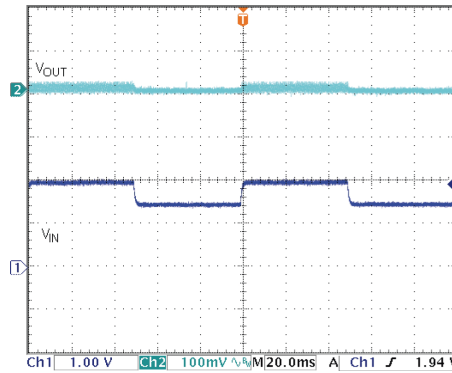


Fig 12. Line Transient Response
(L=10μH, CIN=COUT=10μF, VIN=1.98V)

HT7730SA

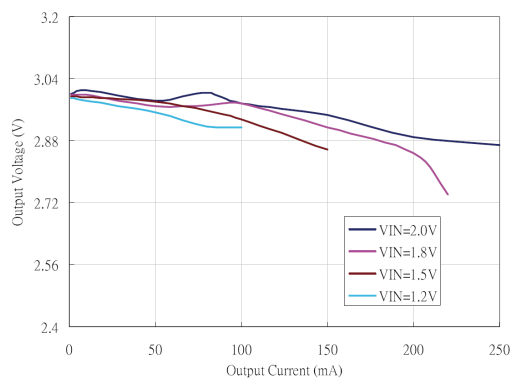


Fig 13. Output Voltage vs. Output Current

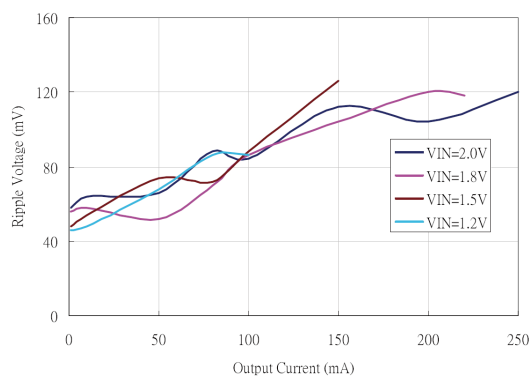


Fig 16. Ripple Voltage vs. Output Current

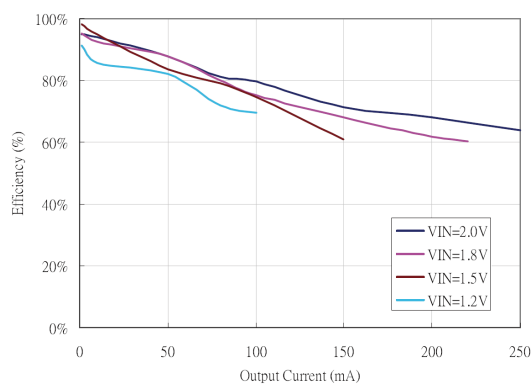


Fig 14. Efficiency vs. Output Current

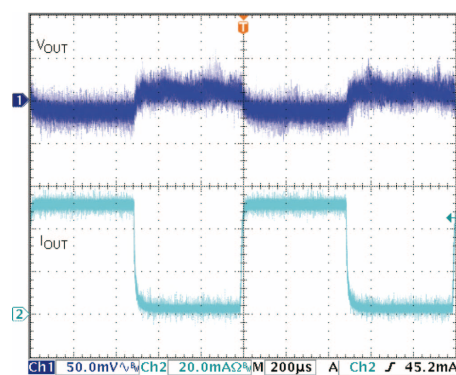


Fig 17. Load Transient Response
($L=10\mu\text{H}$, $C_{\text{IN}}=C_{\text{OUT}}=10\mu\text{F}$, $V_{\text{IN}}=1.8\text{V}$)

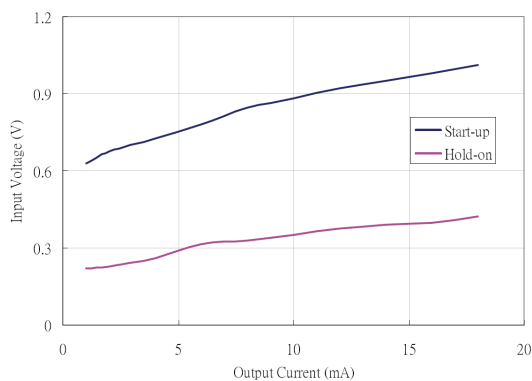


Fig 15. Start-up & Hold-on Voltage

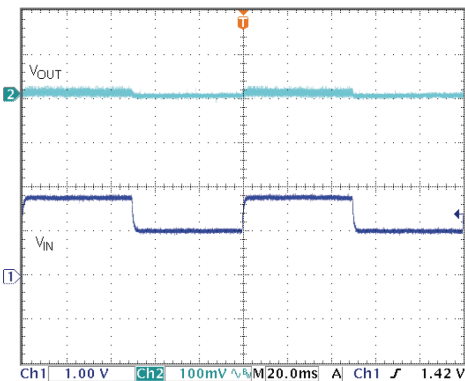
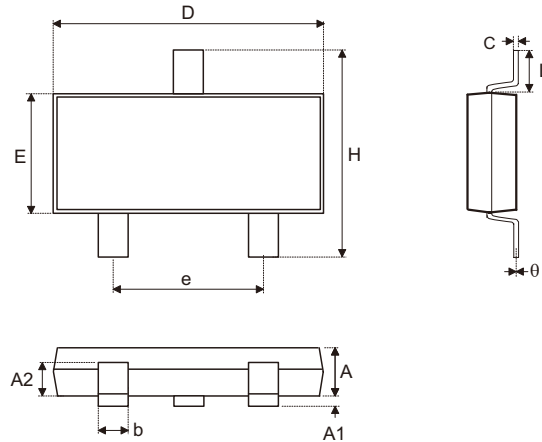


Fig 18. Line Transient Response
($L=10\mu\text{H}$, $C_{\text{IN}}=C_{\text{OUT}}=10\mu\text{F}$, $V_{\text{IN}}=1.8\text{V}$)

Package Information

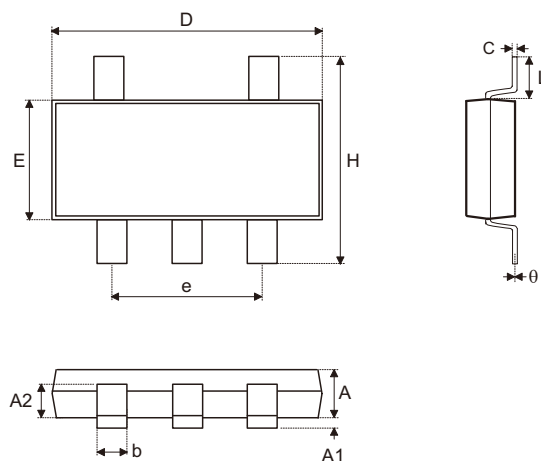
Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the Holtek website (<http://www.holtek.com.tw/english/literature/package.pdf>) for the latest version of the package information.

3-pin SOT23 Outline Dimensions



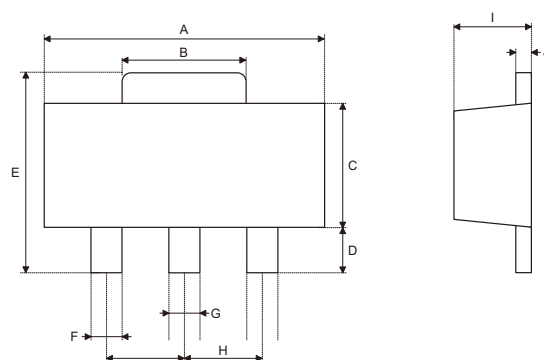
Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.039	—	0.051
A1	—	—	0.004
A2	0.028	—	0.035
b	0.014	—	0.020
C	0.004	—	0.010
D	0.106	—	0.122
E	0.055	—	0.071
e	—	0.075	—
H	0.102	—	0.118
L	0.015	—	—
θ	0°	—	9°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	1.00	—	1.30
A1	—	—	0.10
A2	0.70	—	0.90
b	0.35	—	0.50
C	0.10	—	0.25
D	2.70	—	3.10
E	1.40	—	1.80
e	—	1.90	—
H	2.60	—	3.00
L	0.37	—	—
θ	0°	—	9°

5-pin SOT23-5 Outline Dimensions


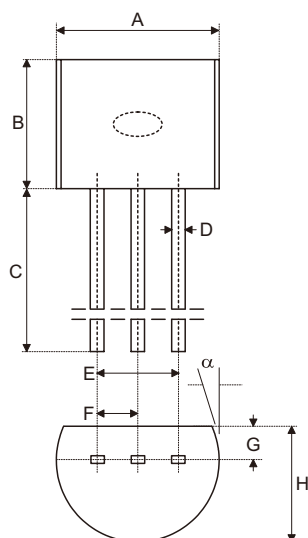
Symbol	Dimensions in inch		
	Min.	Nom.	Max.
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A1	—	—	0.004
A2	0.028	—	0.035
b	0.014	—	0.020
C	0.004	—	0.010
D	0.106	—	0.122
E	0.055	—	0.071
e	—	0.075	—
H	0.102	—	0.118
L	0.015	—	—
θ	0°	—	9°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	1.00	—	1.30
A1	—	—	0.10
A2	0.70	—	0.90
b	0.35	—	0.50
C	0.10	—	0.25
D	2.70	—	3.10
E	1.40	—	1.80
e	—	1.90	—
H	2.60	—	3.00
L	0.37	—	—
θ	0°	—	9°

3-pin SOT89 Outline Dimensions


Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.173	—	0.181
B	0.059	—	0.072
C	0.090	—	0.102
D	0.035	—	0.047
E	0.155	—	0.167
F	0.014	—	0.019
G	0.017	—	0.022
H	—	0.059	—
I	55	—	63
J	14	—	17

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	4.39	—	4.60
B	1.50	—	1.83
C	2.29	—	2.59
D	0.89	—	1.19
E	3.94	—	4.24
F	0.36	—	0.48
G	0.43	—	0.56
H	—	1.50	—
I	1.40	—	1.60
J	0.36	—	0.43

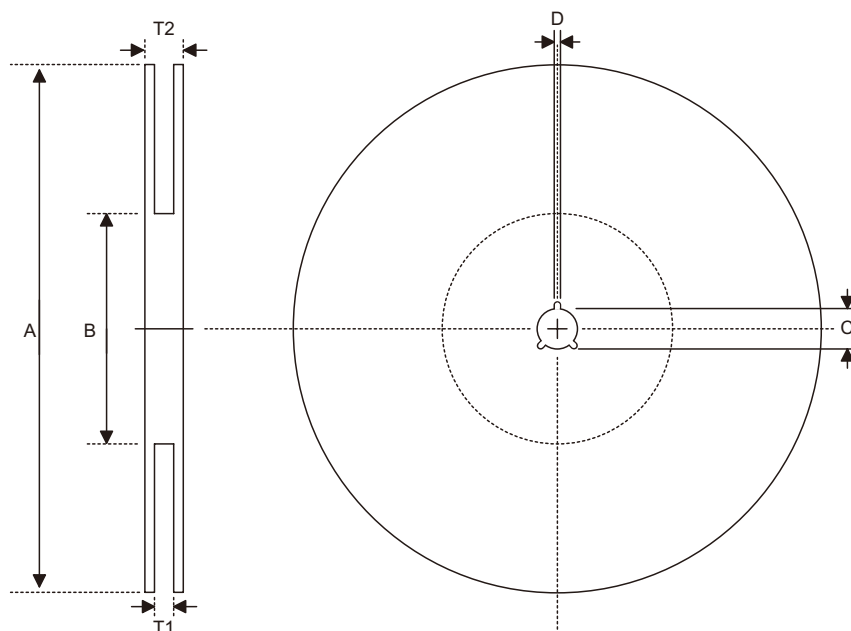
3-pin TO92 Outline Dimensions


Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.170	—	0.200
B	0.170	—	0.200
C	0.500	—	—
D	0.011	—	0.020
E	0.090	—	0.110
F	0.045	—	0.055
G	0.045	—	0.065
H	0.130	—	0.160
α	0°	—	10°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	4.32	—	5.08
B	4.32	—	5.08
C	12.70	—	—
D	0.28	—	0.51
E	2.29	—	2.79
F	1.14	—	1.40
G	1.14	—	1.65
H	3.30	—	4.06
α	0°	—	10°

Product Tape and Reel Specifications

Reel Dimensions



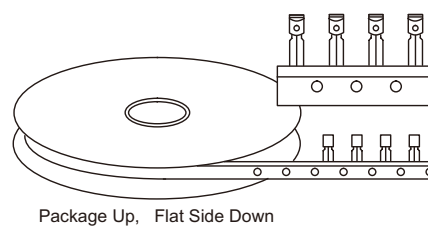
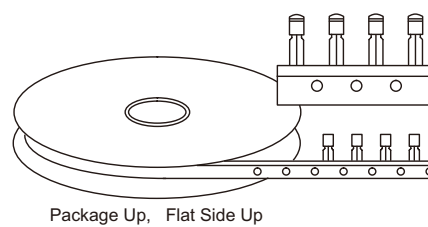
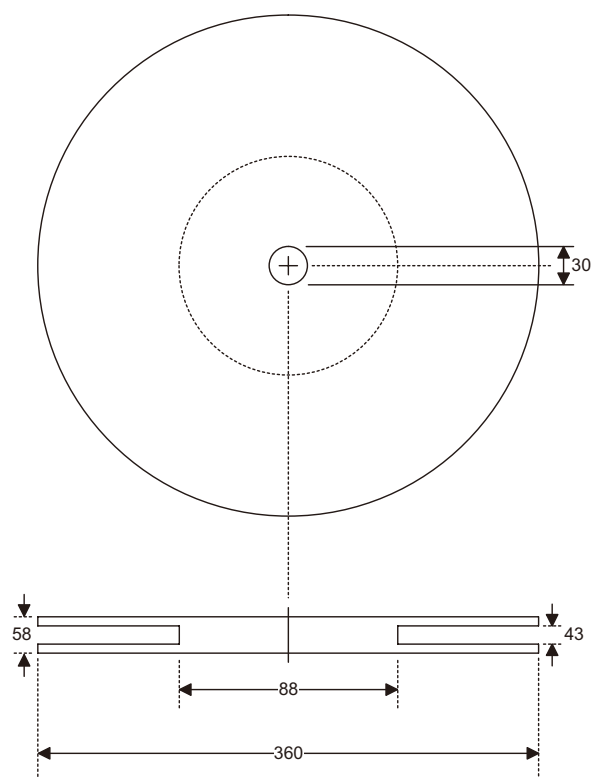
SOT23-3, SOT23-5

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	178.0±1.0
B	Reel Inner Diameter	62.0±1.0
C	Spindle Hole Diameter	13.0±0.2
D	Key Slit Width	2.50±0.25
T1	Space Between Flange	8.4 ^{+1.5/-0.0}
T2	Reel Thickness	11.4 ^{+1.5/-0.0}

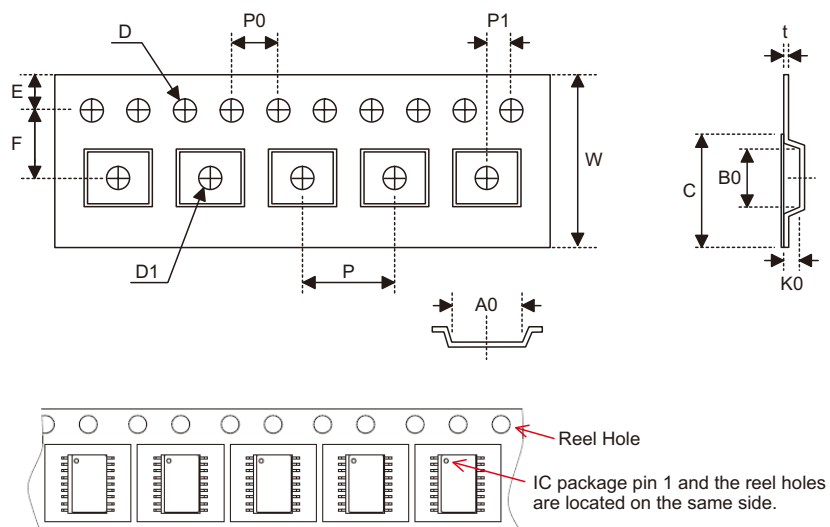
SOT89-3

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	178.0±1.0
B	Reel Inner Diameter	62.0±1.0
C	Spindle Hole Diameter	13.0±0.2
D	Key Slit Width	2.50±0.25
T1	Space Between Flange	8.4 ^{+1.5/-0.0}
T2	Reel Thickness	11.4 ^{+1.5/-0.0}

TO92 Reel Dimensions (Unit: mm)



Carrier Tape Dimensions



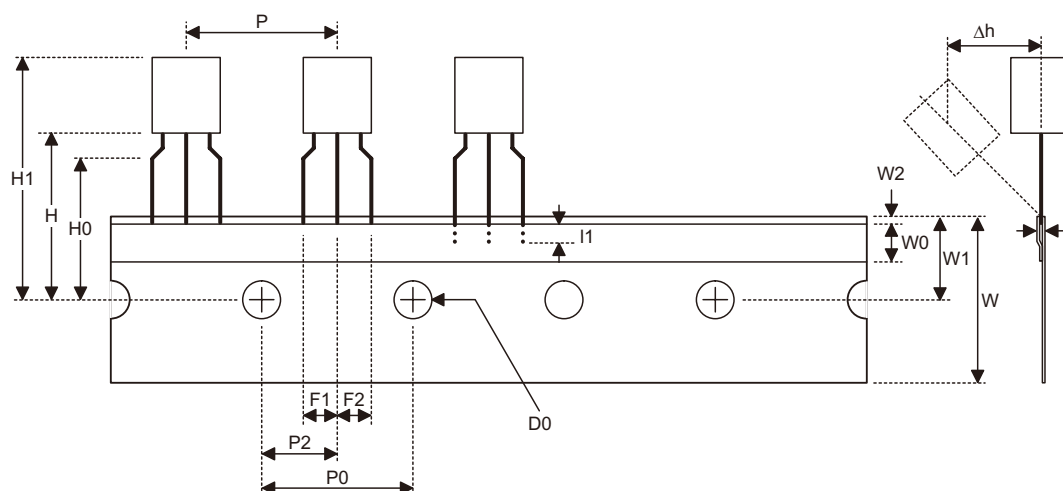
SOT23-3, SOT23-5

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	8.0±0.3
P	Cavity Pitch	4.0±0.1
E	Perforation Position	1.75±0.10
F	Cavity to Perforation (Width Direction)	3.50±0.05
D	Perforation Diameter	1.5 ^{+0.1/-0.00}
D1	Cavity Hole Diameter	1.5 ^{+0.1/-0.00}
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.00±0.05
A0	Cavity Length	3.15±0.10
B0	Cavity Width	3.2±0.1
K0	Cavity Depth	1.4±0.1
t	Carrier Tape Thickness	0.20±0.03
C	Cover Tape Width	5.3±0.1

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Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0 ^{+0.3/-0.1}
P	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.10
F	Cavity to Perforation (Width Direction)	5.50±0.05
D	Perforation Diameter	1.5 ^{+0.1/-0.00}
D1	Cavity Hole Diameter	1.5 ^{+0.1/-0.00}
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	4.8±0.1
B0	Cavity Width	4.5±0.1
K0	Cavity Depth	1.8±0.1
t	Carrier Tape Thickness	0.300±0.013
C	Cover Tape Width	9.3±0.1

Carrier Tape Dimensions



T092

Symbol	Description	Dimensions in mm
I1	Taped Lead Length	(2.5)
P	Component Pitch	12.7±1.0
P0	Perforation Pitch	12.7±0.3
P2	Component to Perforation (Length Direction)	6.35±0.40
F1	Lead Spread	2.5 ^{+0.4/-0.0}
F2	Lead Spread	2.5 ^{+0.4/-0.0}
Δh	Component Alignment	0.0±0.1
W	Carrier Tape Width	18.0 ^{+1.0/-0.5}
W0	Hold-down Tape Width	6.0±0.5
W1	Perforation Position	9.0±0.5
W2	Hold-down Tape Position	(0.5)
H0	Lead Clinch Height	16.0±0.5
H1	Component Height	Less than 24.7
D0	Perforation Diameter	4.0±0.2
t	Taped Lead Thickness	0.7±0.2
H	Component Base Height	19.0±0.5

Note: Thickness less than 0.38±0.05mm~0.5mm.
P0 Accumulated pitch tolerance: ±1mm/20pitches.
() Bracketed figures are for reference only.

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